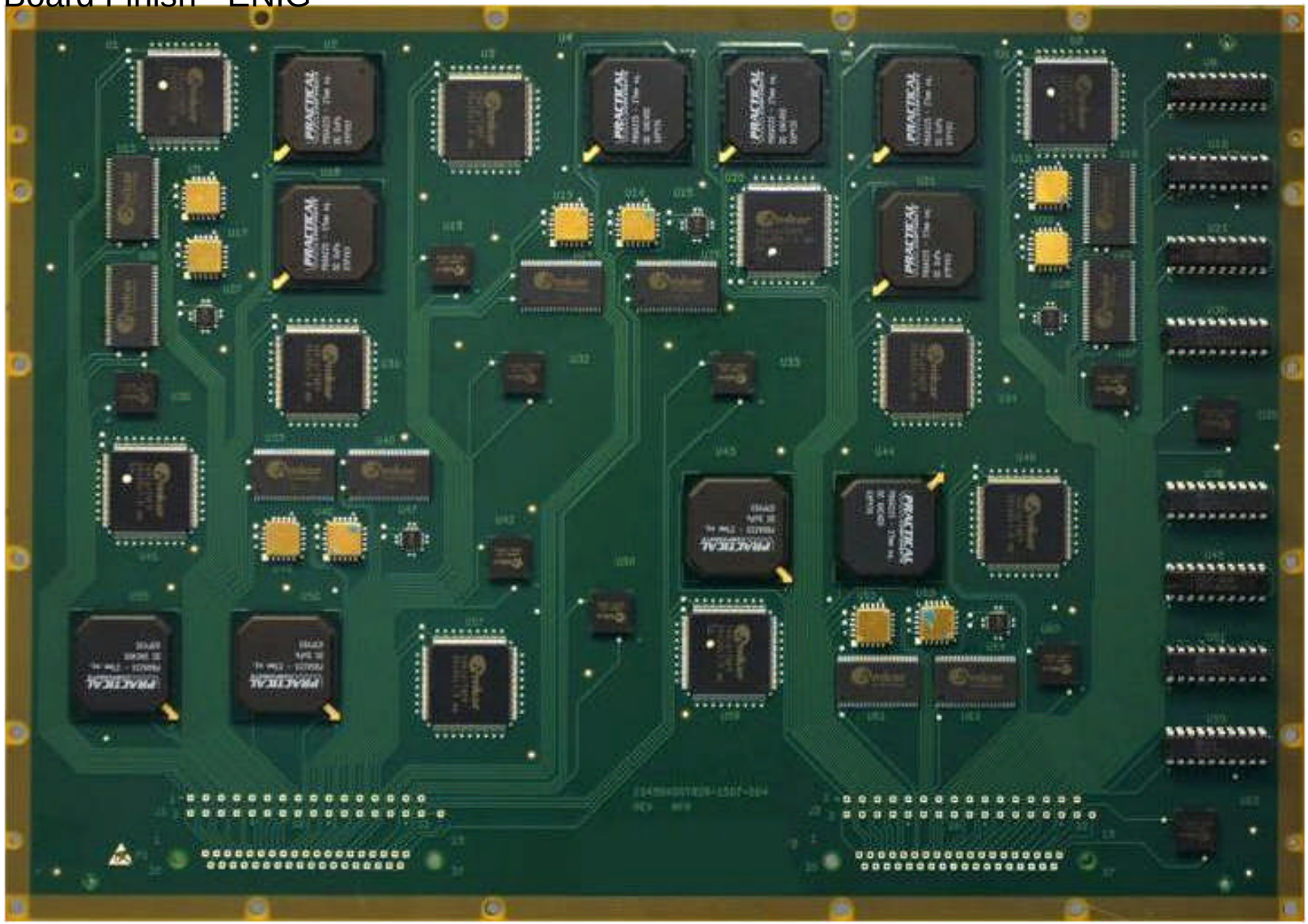
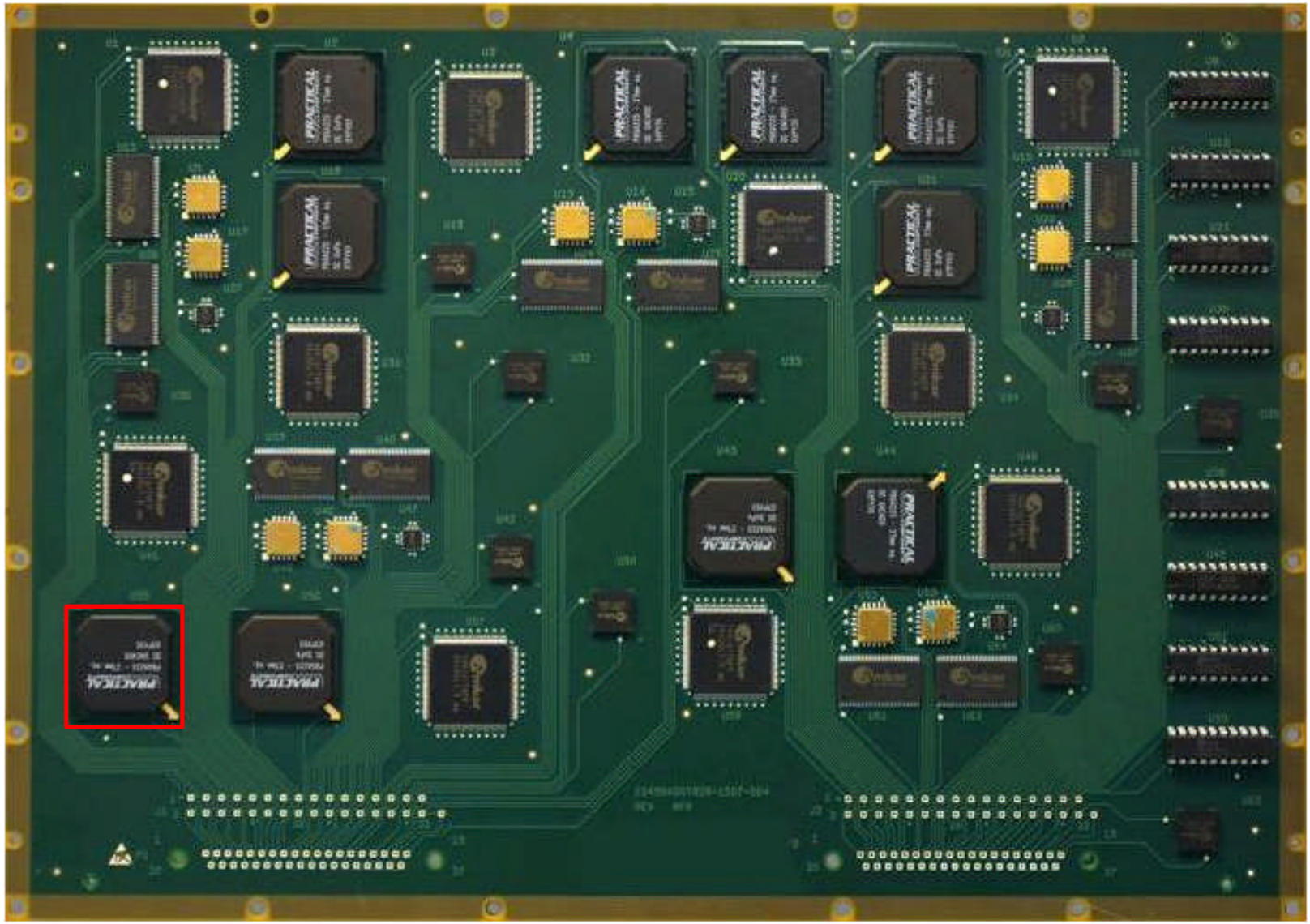
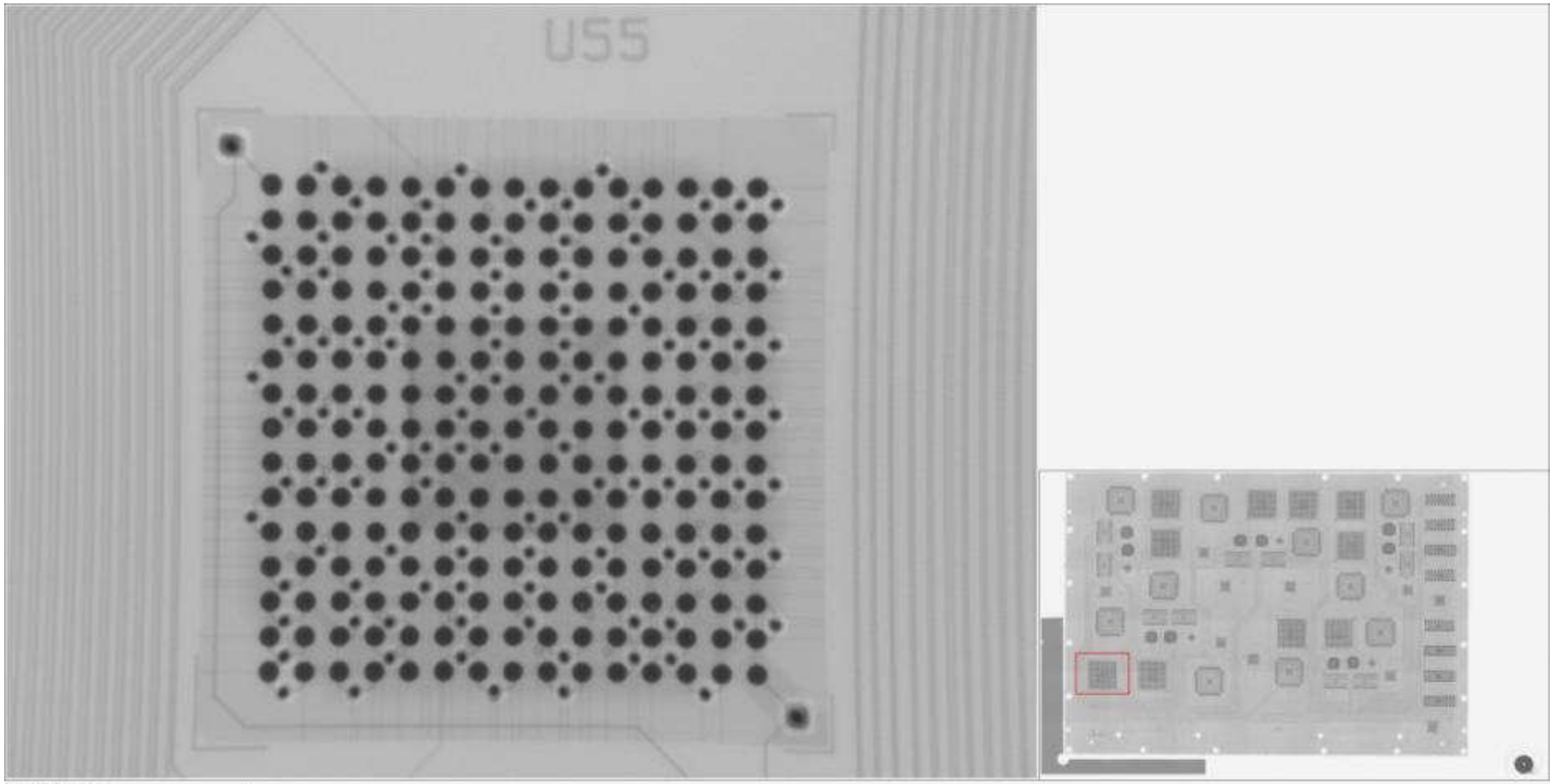
SN93 - Lead-Free Manufactured; Thermal Cycle and Combined Environments Test Vehicle

- Assembly Profile – Lead-Free
- Reflow Solder – SAC305
- Wave Solder – SN100C
- Board Finish - ENIG



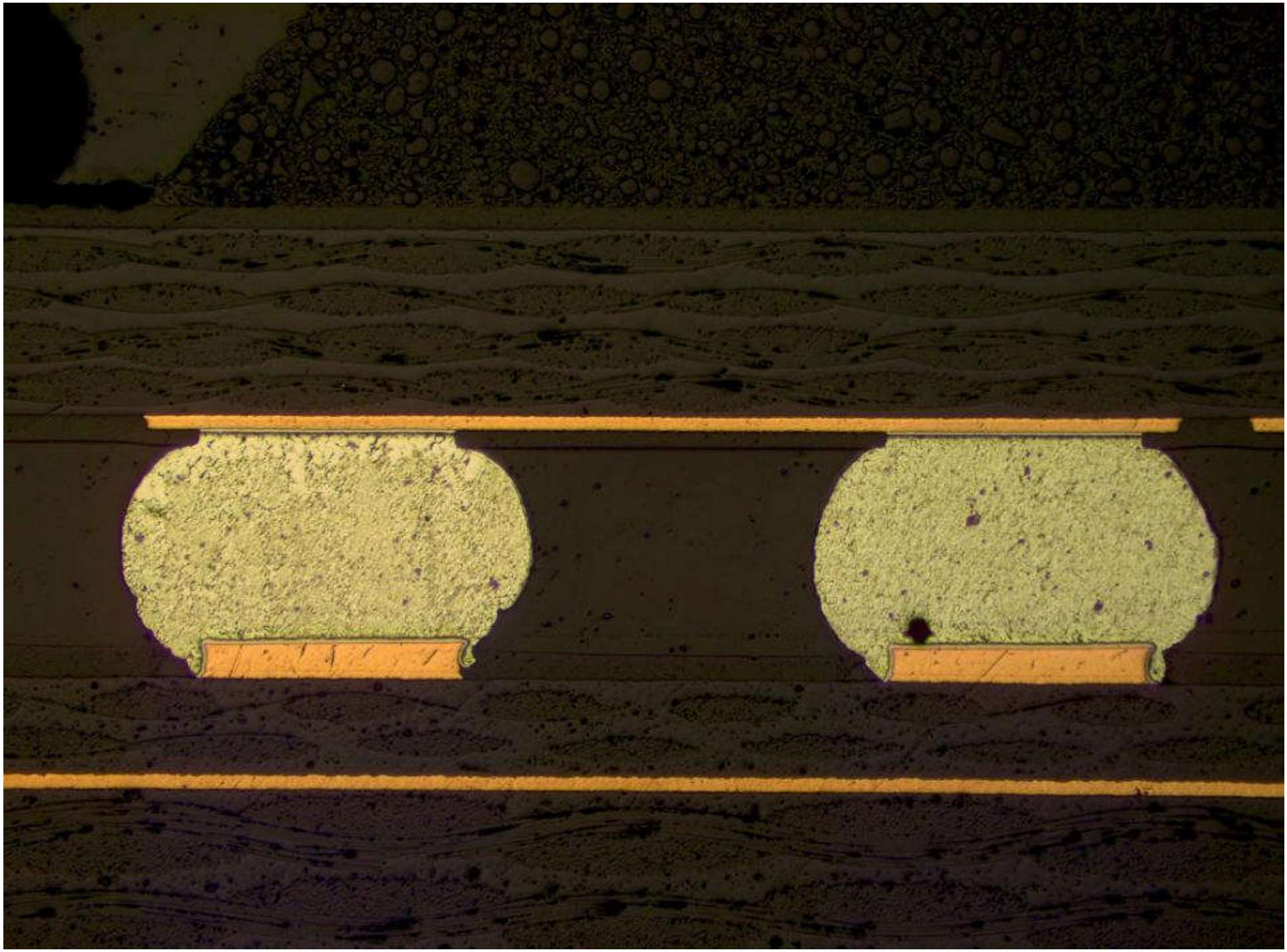
U55 – BGA-225
SnPb Finish

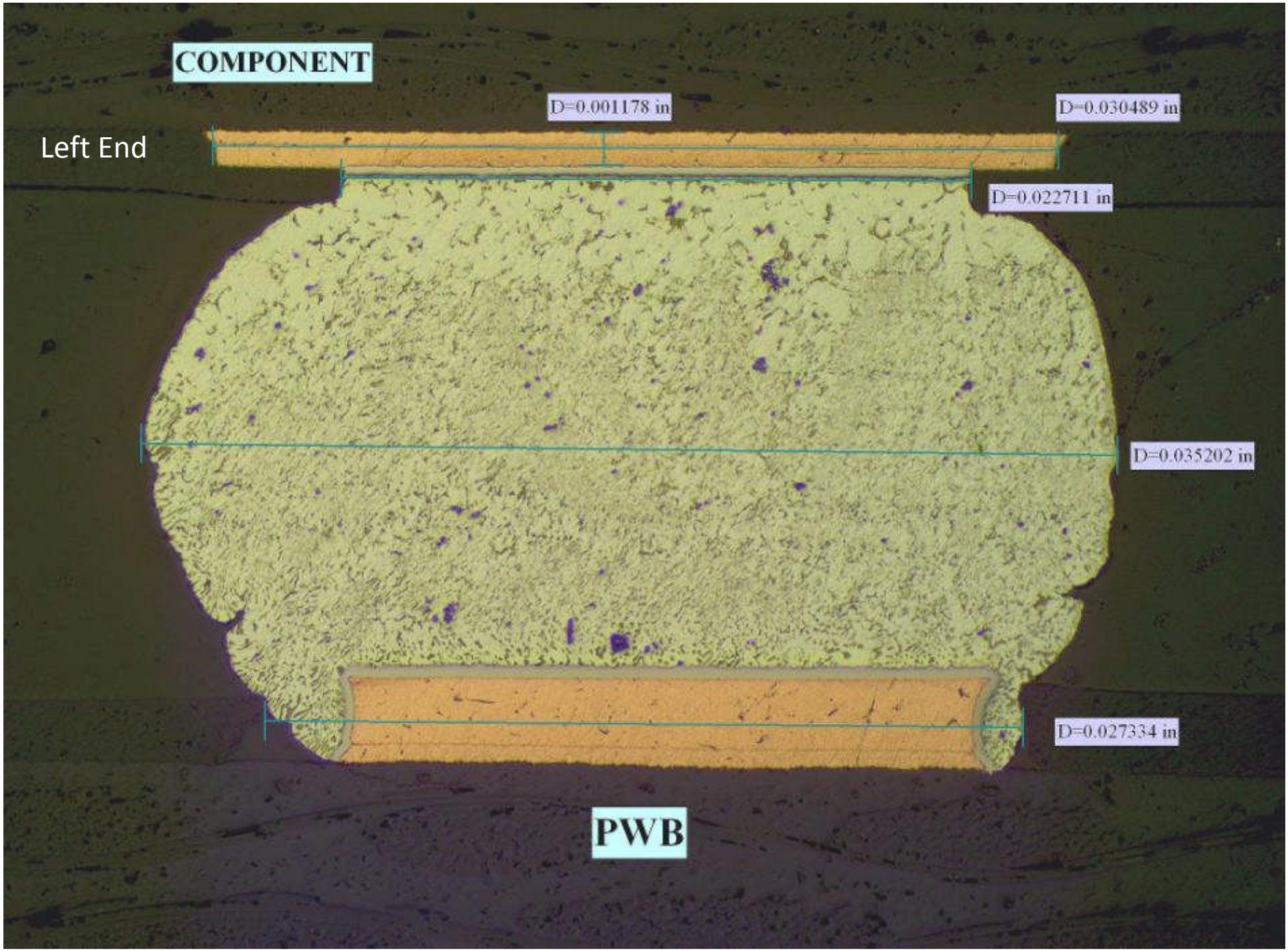


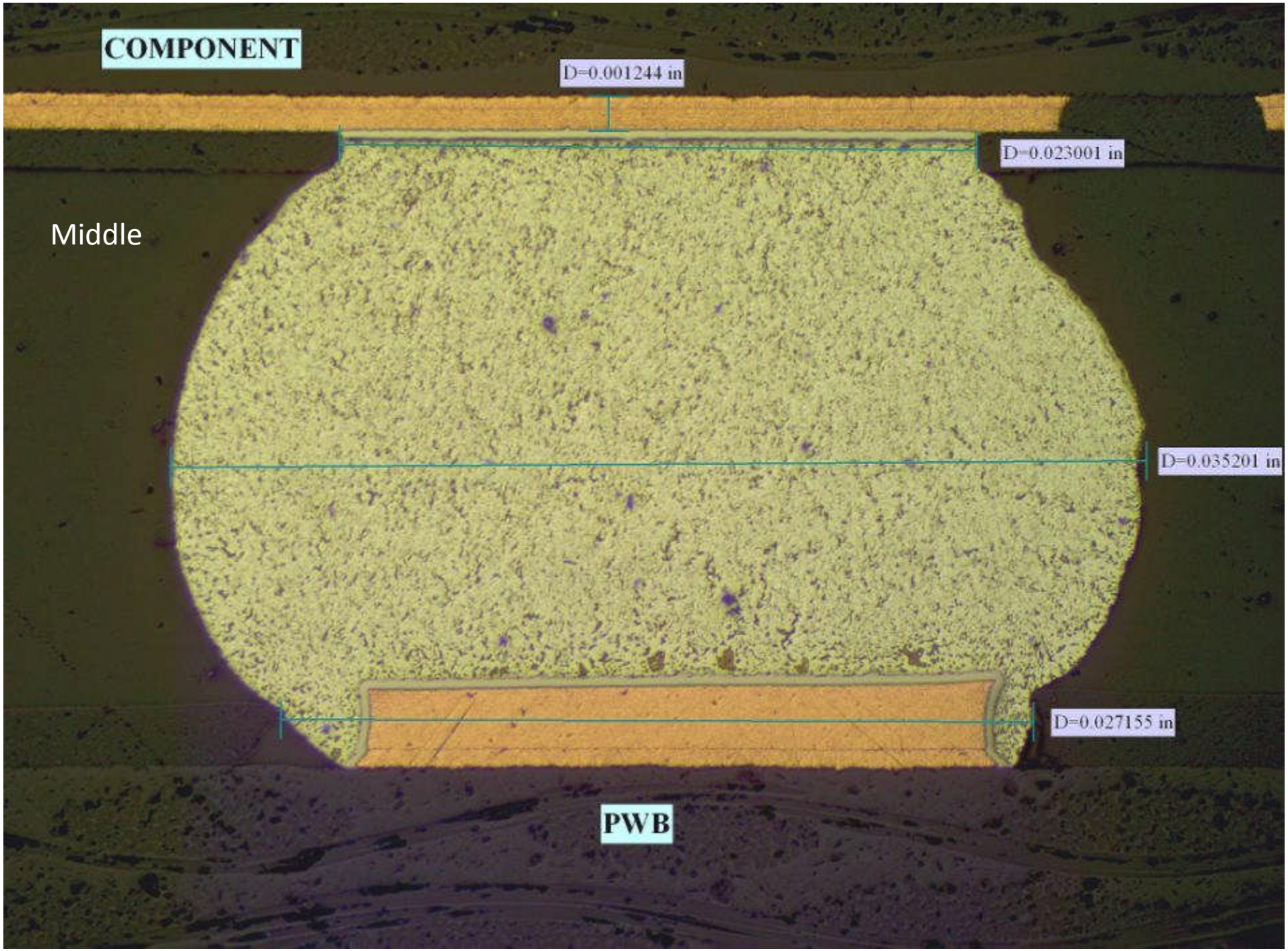


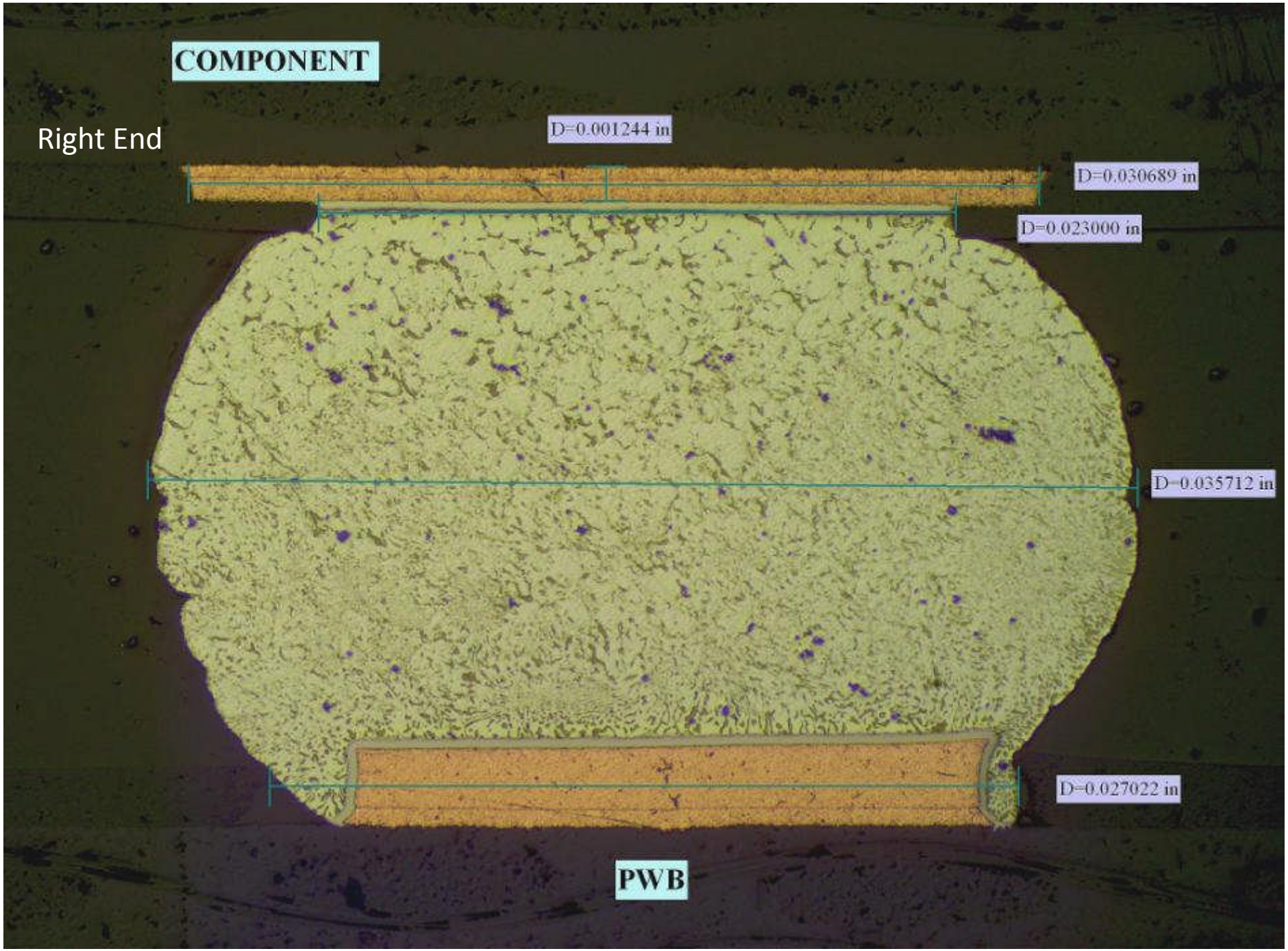

10.0mm

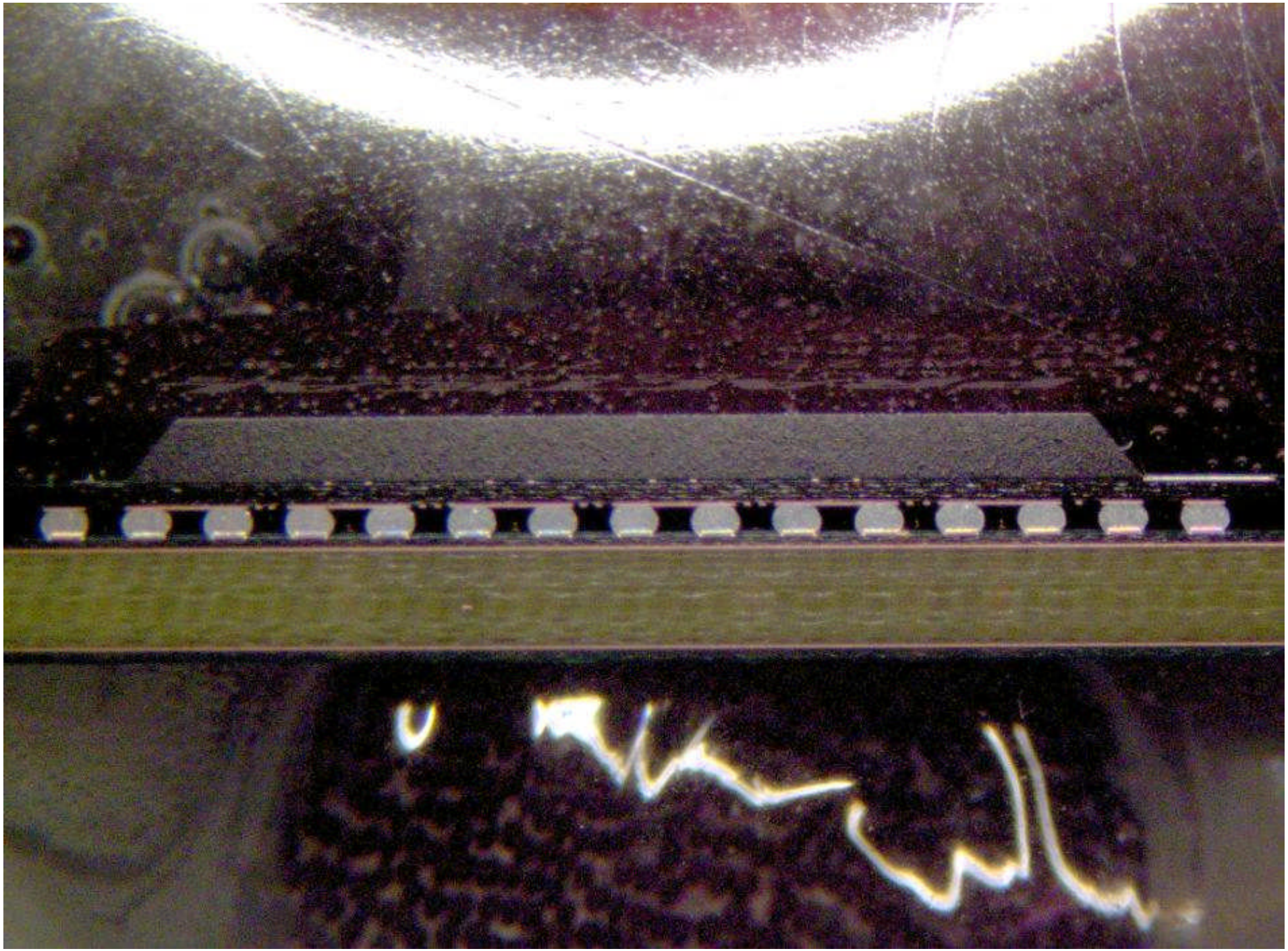
Tube voltage: 115 kV
Tube power: 1.67 W
Filter method used: None
Averaging: 256 frames

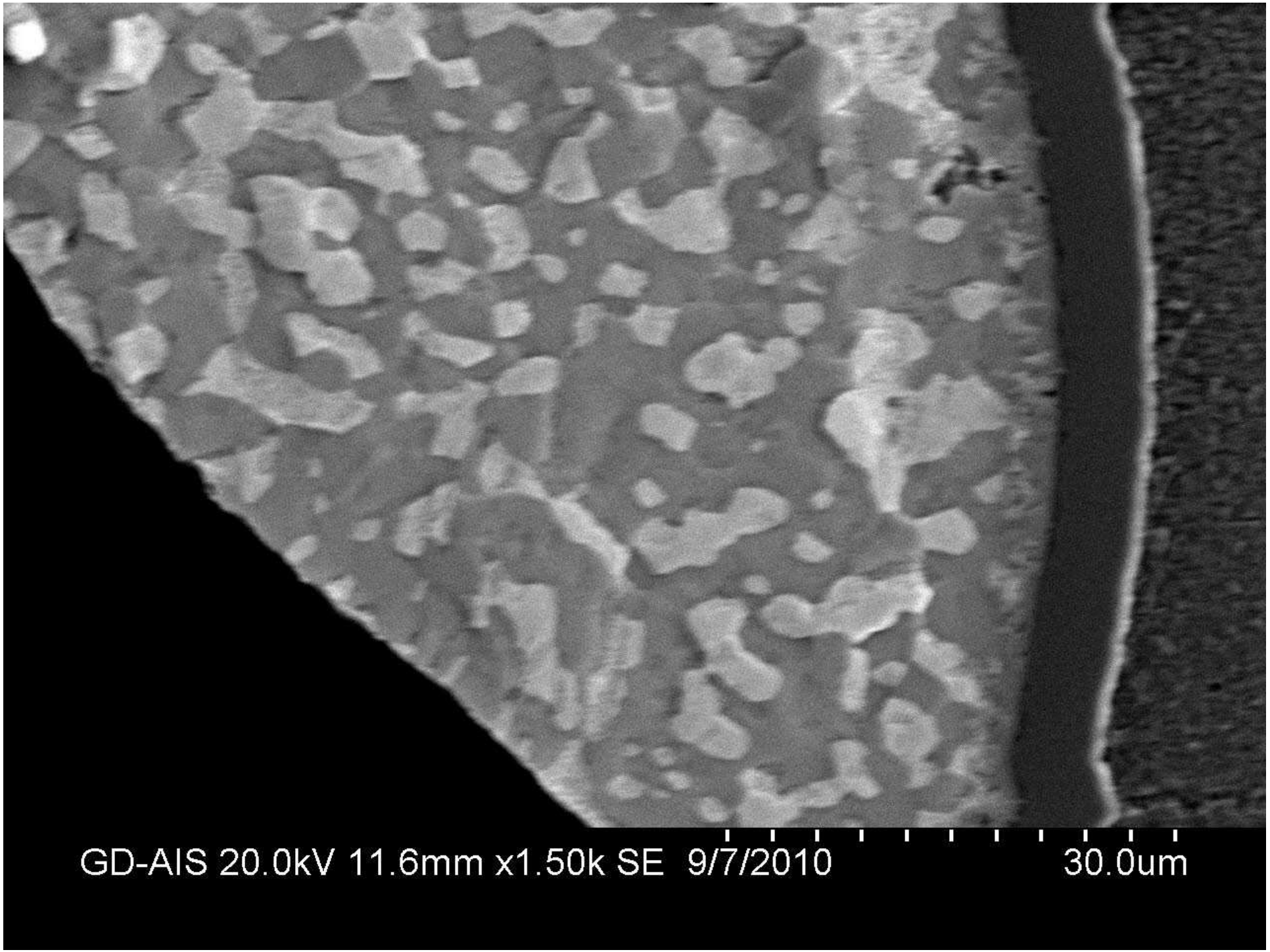


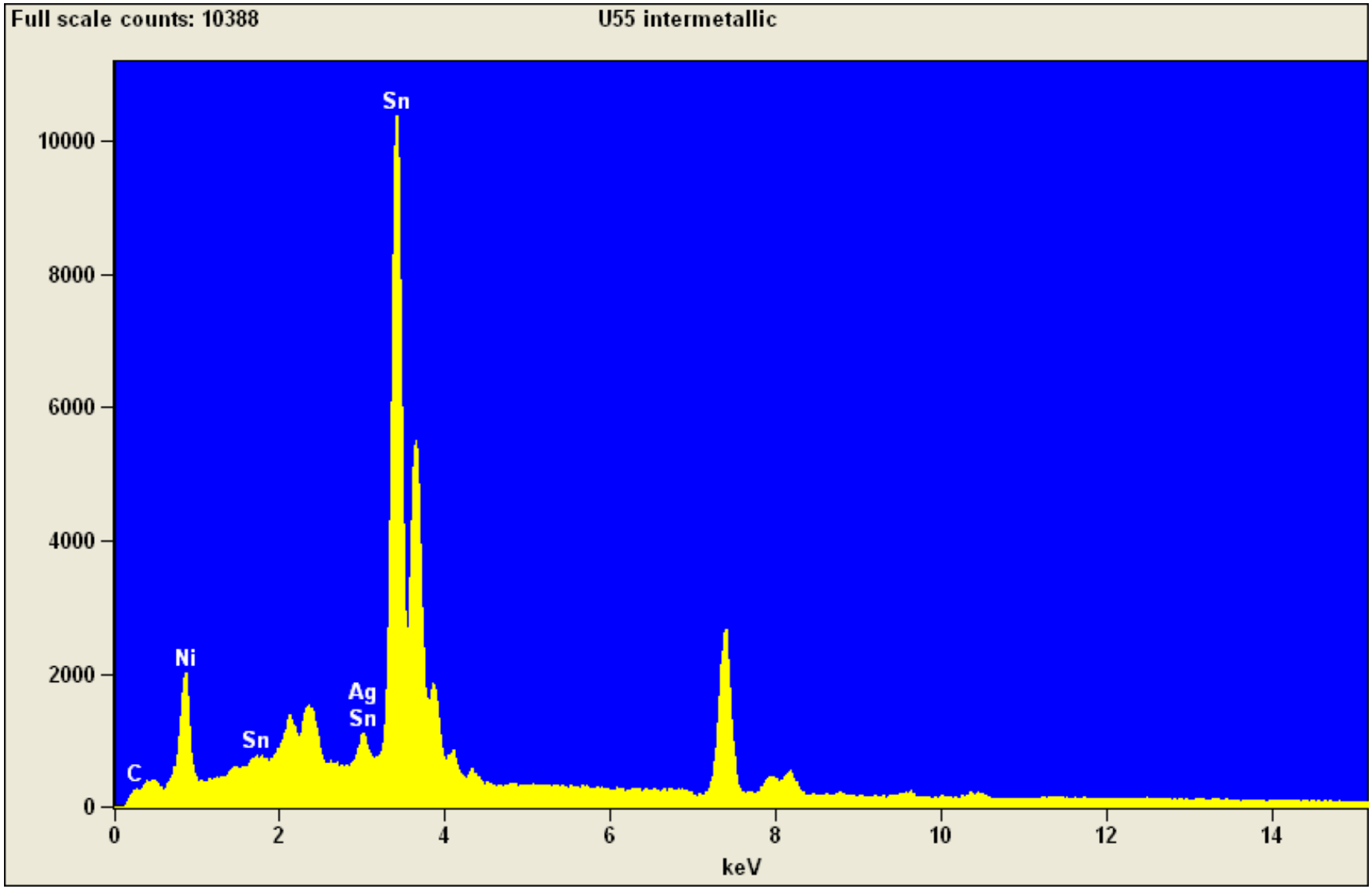

COMPONENT
Left End
D=0.001178 in
D=0.030489 in
D=0.022711 in
D=0.035202 in
D=0.027334 in
PWB


COMPONENT
D=0.001244 in
D=0.023001 in
Middle
D=0.035201 in
D=0.027155 in
PWB


COMPONENT
Right End
D=0.001244 in
D=0.030689 in
D=0.023000 in
D=0.035712 in
D=0.027022 in
PWB




GD-AIS 20.0kV 11.6mm x1.50k SE 9/7/2010
30.0um




Quantitative Results for: U55 intermetallic

| Element Line | Weight % | Atom % |
|---|---|---|
| Ni K | 23.51 | 38.27 |
| Ag L | 1.76 | 1.56 |
| Sn L | 74.73 | 60.17 |
| Total | 100.00 | 100.00 |